

SOT1784-1

wafer level chip-scale package, 89 bumps, 0.4 mm pitch, 3.63 mm x 3.58 mm x 0.38 mm body

1 September 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP89
Package type industry code	WLCSP89
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	5-9-2016
Manufacturer package code	SOT1784

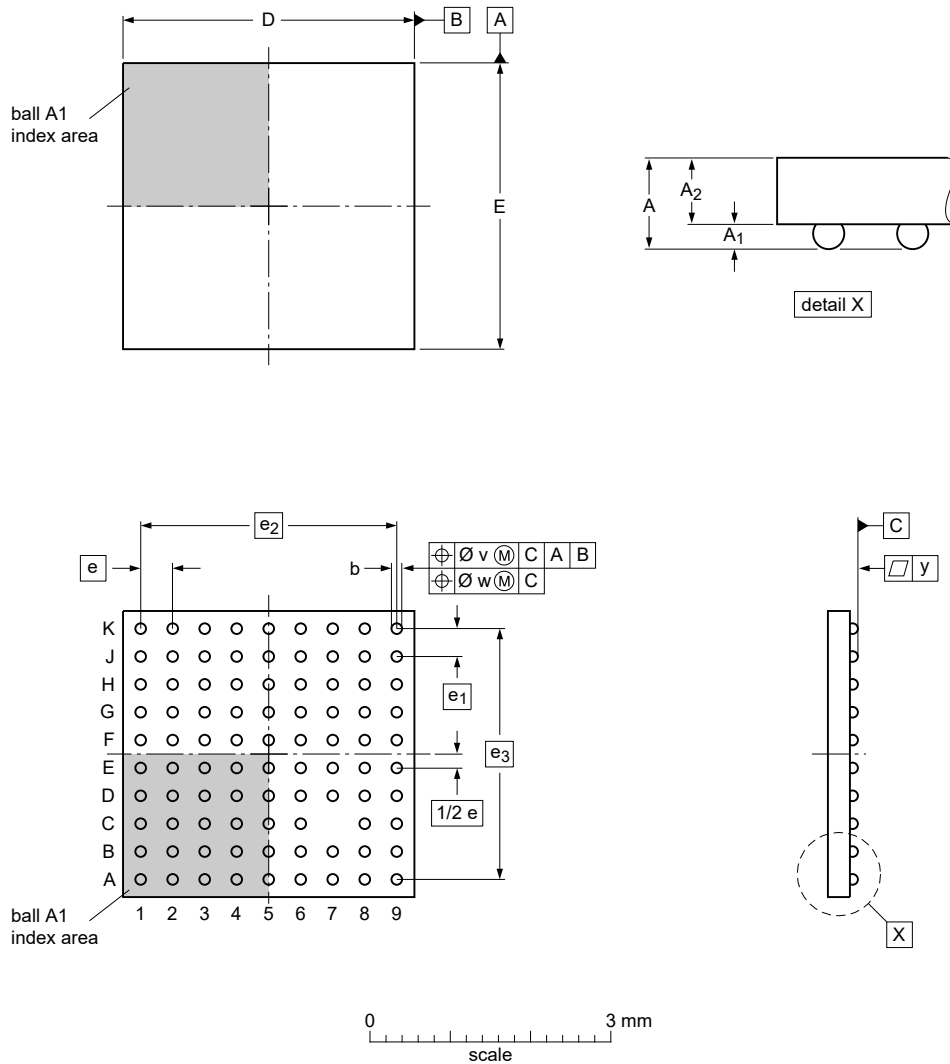
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.6	-	3.63	3.66	mm
E	package width	3.55	-	3.58	3.61	mm
A	seated height	0.35	-	0.38	0.41	mm
A ₂	package height	0.255	-	0.28	0.305	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	89	-	



2. Package outline

WLCSP89: wafer level chip-scale package; 89 bumps; 3.58 x 3.63 x 0.38 mm SOT1784-1



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	e ₃	v	w	y
max	0.41	0.115	0.305	0.145	3.66	3.61							
mm nom	0.38	0.100	0.280	0.130	3.63	3.58	0.4	0.35	3.2	3.15	0.15	0.05	0.02
min	0.35	0.085	0.255	0.115	3.60	3.55							

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
sot1784-1		---			-16-01-04- 16-07-26

Fig. 1. Package outline WLCSP89 (SOT1784-1)

3. Legal information

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Date of release: 1 September 2017
